Bencent®

BGO1001A05-LC2

Order Code: BGO1001A05-LC2

Bencent Composite Product

Version: A2 2018-7-13

Features

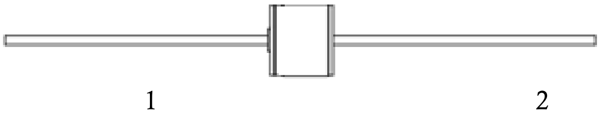
- Size DesignΦ8×7mm
- High Current Handling Capability 5,000A @ 8/20μ s
- Low Capacitance and Insertion Loss
- Fast Response and Long Service Life
- Reliable to Protect Electrostatic Surge
- Moisture sensitivity level： Level 1
- Current Limiting, available 1-40A @1200/950VAC

Exterior

Application Information

- AC Power

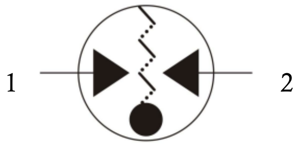
Package (Top View)



Agency Approvals

Icon	Description
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
Pb	Mean lead free
UL	Compliance with UL1449, Certificated E337906

Schematic Symbol



Electrical Parameter

DC Breakdown Voltage[1) 2)]	100V/s	>800	V
Impulse Spark-over Voltage	at 1kV/μs	for 99 % of measured values ≤2000	V
Impulse Discharge Current[3)]	8/20μs ±5times	5	KA
Arc Voltage	at 1A	~60	V
Insulation Resistance	DC=100V	≥1	GΩ
Capacitance at 1 MHz	V_{DC}=0.5V	≤1.5	pF
Weight		~1.62	g
Operating and storage Temperature		-40-125	℃
Marking		Bencent Log 1000	

1) At delivery AQL 0.65 level II ISO 2859
2) In ionized mode
3) Terms and current waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

Open Characteristic

Voltage Rating(V)	1200	1200	1200	1200	1200	1200	1200	950
Ampera Rating(A)	1.2	2	6	12	21.8	24	30	40
Open Time(S) Max.	5	4	2	1.5	1	1	1	1

Note: Heat shrinkable tube and encapsulating are not recommended to use on the surface of BGO product.

Part Numbering System

BGO 1001 A05 L C 2

(1) (2) (3) (4) (5) (6)

(1)Bencent Open GDT
(2)Rated DC Breakdown Voltage, 1001:100*10^1=1000V
(3)Surge Rating, A05: 8/20μs 5KA
(4)Structure, L: Axial Lead
(5)Dimension, C: Φ8×7mm
(6)Pin Number, 2pin

Product Characteristics

Lead Material	Copper & Trio-nickel
Body Material	Ceramics
Terminal Finish	100% Matte-Tin Plated

Environmental Reliability Characteristics

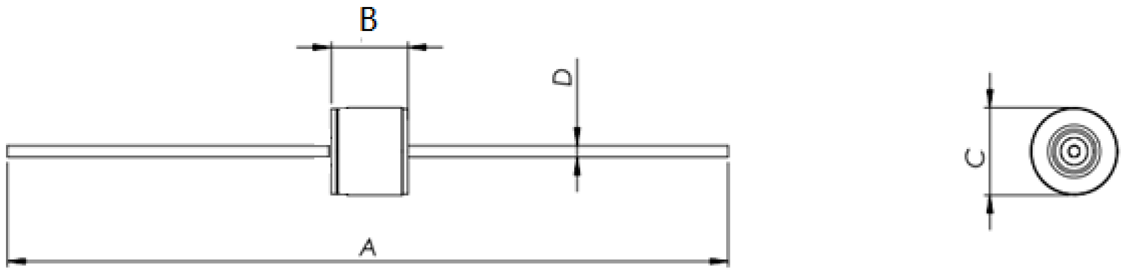
Testing items	Technical standards
High Temperature Storage Test	Temperature: 125℃ Time:2H
Low Temperature Storage Test	Temperature: -40℃ Time:2H
Thermal Shock	Temperature:-40-125℃ Cycle:50
Vibration	Frequency：10-500Hz Amplitude：0.15mm Time：45mins
Resistance of soldering heat	Temperature: 260±5℃ Time of dip soldering：10s，1time

Note: Up-screen program can be specified by customer’s request via contacting Bencent service

Solderability Test

Solderability	Solder Pot Temperature:	245℃ ±5℃
	Solder Dwell Time:	4-6 seconds

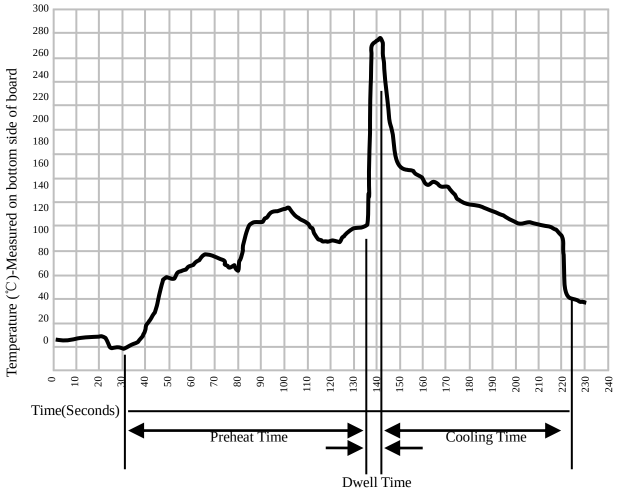
Product Dimensions



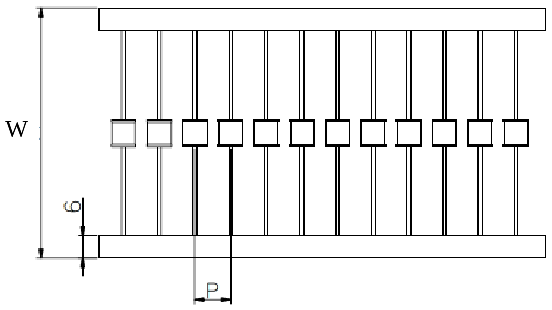
REF	Mm	inch
A	64±4	2.520±0.157
B	7±1.4	0.276±0.055
C	Φ8±0.2	Φ0.315±0.008
D	Φ0.8±0.1	Φ0.039±0.004

Wave Soldering Profile

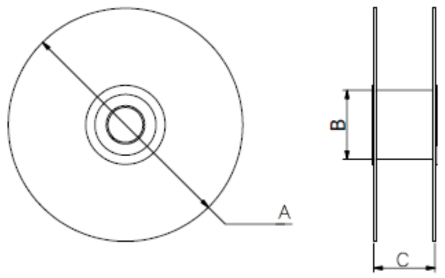
Wave Soldering Condition		**Pb-Free assembly**
Pre Heat	Temperature Min	100°C
	Temperature Max	150°C
	Time （min to max）	60 – 180 secs
Solder Pot Temperature		270℃ Max
Solder Dwell Time		2-5 seconds



Package Reel Information



REF	mm	inch
W	65±3	2.559±0.118
P	10±1	0.394±0.039
A	Φ340±2	Φ13.386±0.079
B	Φ83±2	Φ3.268±0.079
C	73±3	2.874±0.118



OUTLINE	REEL (PCS)	PER CARTON (PCS)	CARTON SIZE(mm)		
			L	W	H
TAPING	700	4200	480	350	360

单击下面可查看定价，库存，交付和生命周期等信息

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